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(12) **United States Design Patent**
Enderlein et al.

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(54) **CIRCUIT BOARD**

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(**) Term: **14 Years**

(21) Appl. No.: **29/180,813**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
29/829, 843; 174/250, 254, 260, 265; 361/720,
361/736, 748, 760, 761, 773

See application file for complete search history.

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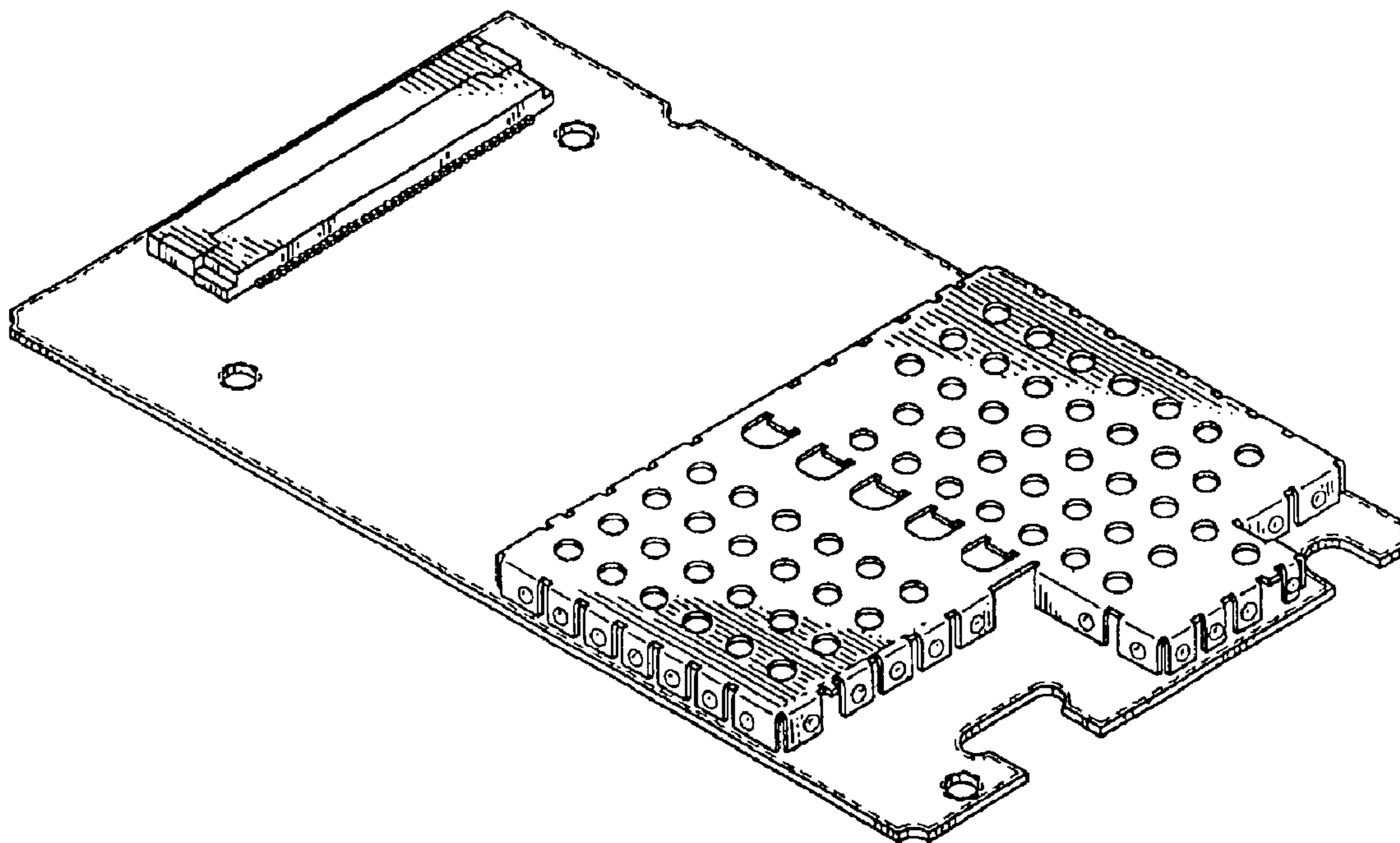
(57) **CLAIM**

The ornamental design for a circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective of the invention.
FIG. 2 is a plan elevation of the invention.
FIG. 3 is a bottom plan of the invention.
FIG. 4 is a front elevation of the invention.
FIG. 5 is a rear elevation of the invention.
FIG. 6 is a right end elevation of the invention; and,
FIG. 7 is a left end elevation of the invention.
The broken lines define the boundary of the claimed design and form no part of the claimed design.

1 Claim, 4 Drawing Sheets



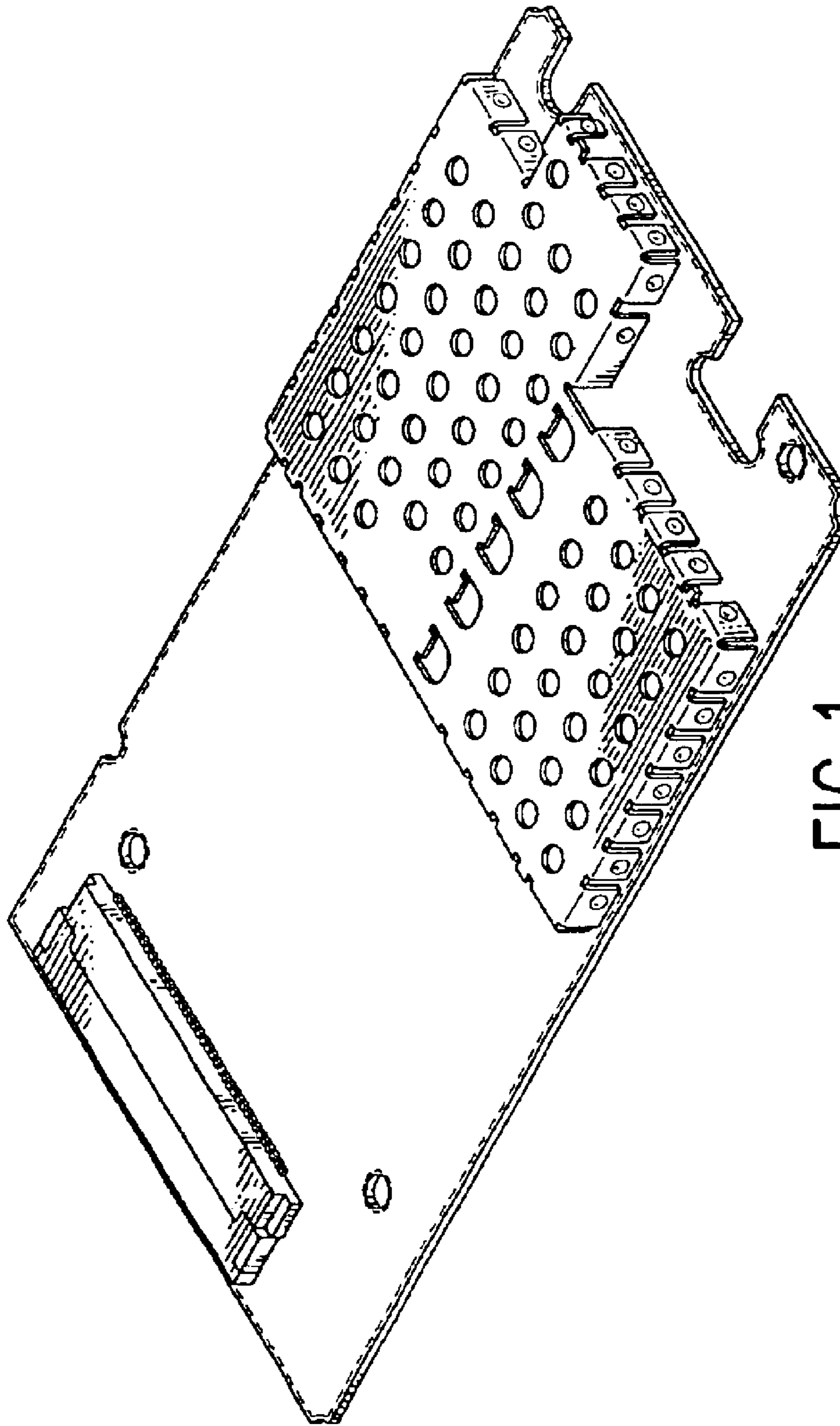


FIG. 1

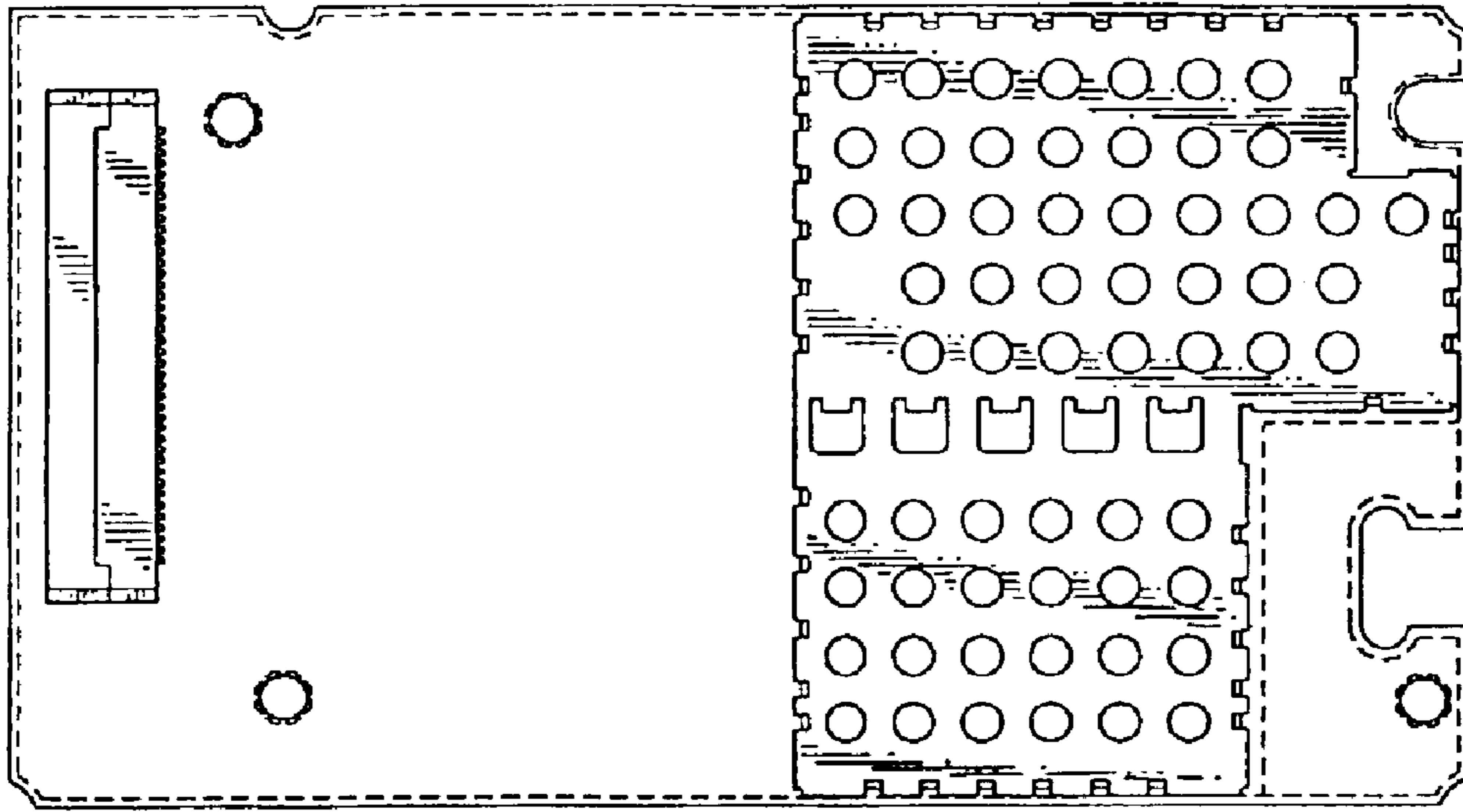


FIG. 2

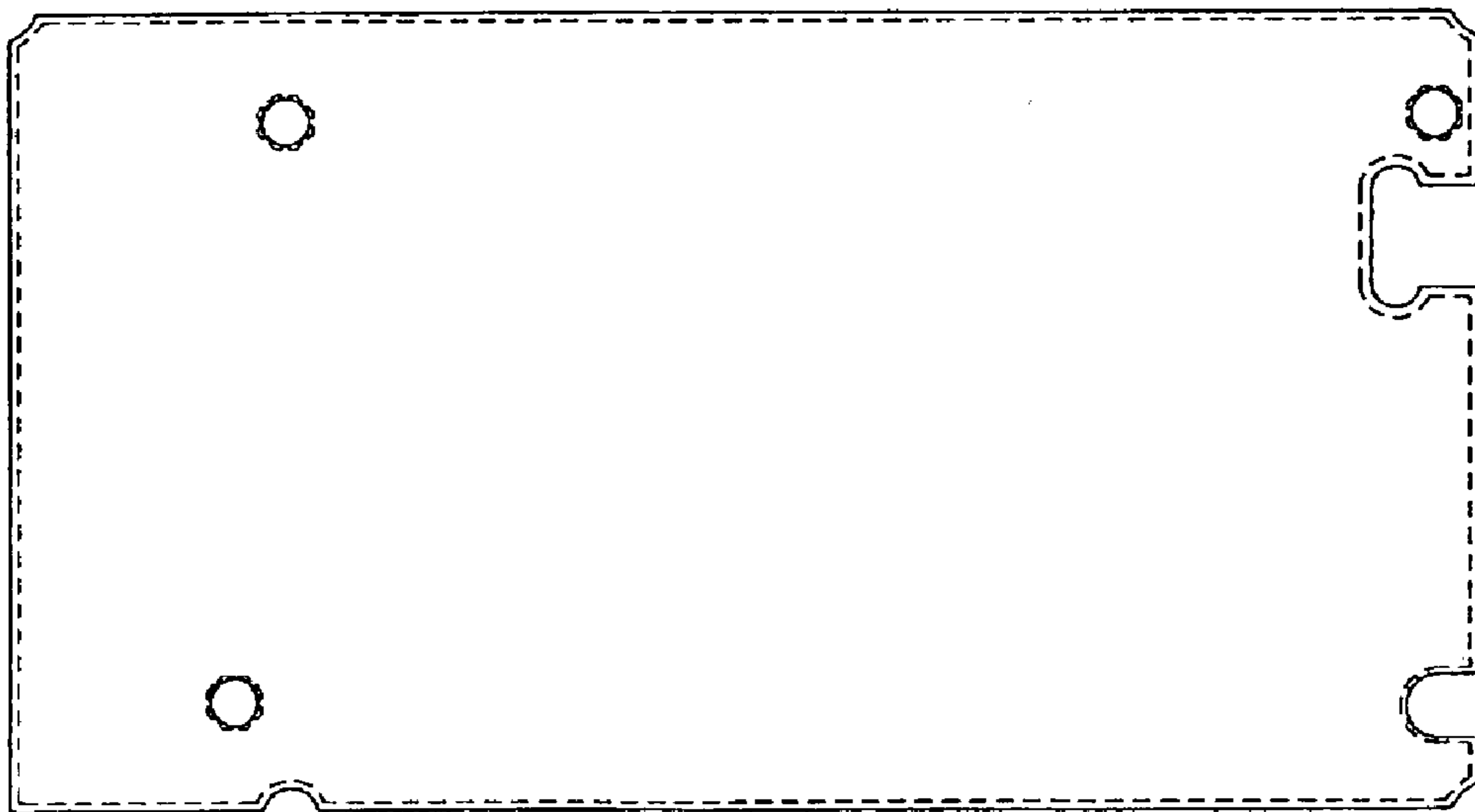


FIG. 3



FIG. 4



FIG. 5



FIG. 6

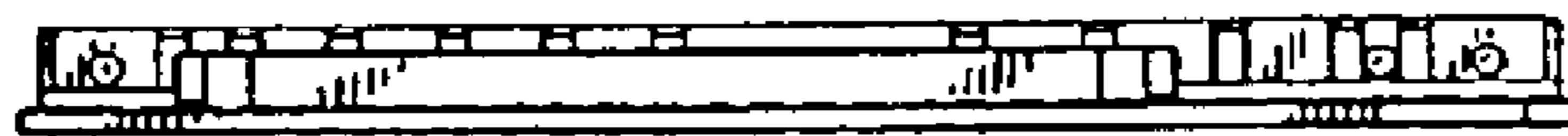


FIG. 7